

Replaced
by Amendment

ABSTRACT

The present invention provides a method of forming a dielectric layer containing dielectric filler, which is excellent in uniformity of a film-thickness, with the use of dielectric filler-containing dielectric layer. In particular, for example, it is a method of forming a dielectric filler-containing polyimide coating on a metallic material through an electrodeposition coating method with the use of a dielectric filler-containing polyimide electrodeposition solution, said solution being a polyimide electrodeposition solution in which a dielectric filler has been contained, wherein the used as a dielectric filler is a globoid dielectric powder having perovskite structure which is 0.05 to 1.0 μm in an average particle size D_{1A} , 0.1 to 2.0 μm in a weight cumulative particle size D_{50} based on a laser diffraction scattering particle size distribution measurement method, and 4.5 or less in a coagulation degree value represented by D_{50}/D_{1A} where the weight cumulative particle size D_{50} and the average particle size D_{1A} obtained from an image analysis.